

IN THE CLAIMS

1 (Currently Amended). A socket comprising:
an upper surface with a ~~plurality of~~ solder ball receiving ~~aperture~~ apertures formed therein; and
a ~~plurality of an~~ S-shaped spring ~~contacts aligned with~~ contact arranged in said ~~apertures aperture, said contact adapted to electrically engage~~ make wiping electrical contact with a solder ball inserted into ~~an aperture~~ said aperture.

Claim 2 (Canceled).

3 (Currently Amended). The socket of claim 1 wherein said spring ~~contacts~~ contact is adapted to make wiping electrical contact with lands.

4 (Original). The socket of claim 1 wherein said S-shaped spring contacts include opposed contact arms, one of which extends upwardly and the other which extends downwardly.

5 (Currently Amended). The socket of claim 1 wherein socket includes a body, said body having a plurality of solder ball receiving ~~said~~ apertures formed therein.

6 (Original). The socket of claim 5 including an alignment feature extending upwardly from said body to align a land grid array package with said socket.

7 (Currently Amended). The socket of claim 1 wherein said spring contact includes ~~contacts include~~ an upwardly extending arm to make contact with an integrated circuit package and a downwardly extending arm to make contact with an underlying circuit board.

8 (Original). The socket of claim 1 wherein said socket includes a body including an upwardly extending protrusion, said protrusion having a height less than the height of a solder ball for a ball grid array package.

9 (Currently Amended). The socket of claim ~~6~~ ~~8~~ wherein said alignment feature is L-shaped.

10 (Original). The socket of claim 9 including two L-shaped alignment features opposed diagonally from one another on said socket.

11 (Currently Amended). An electronic device comprising:
a printed circuit board;
a socket coupled to said printed circuit board, said socket including a housing having an upper surface with a ~~plurality of~~ solder ball receiving aperture ~~apertures~~ formed therein and a ~~plurality of~~ an S-shaped spring contact ~~contacts~~ aligned with said aperture ~~apertures~~ to ~~electrically engage~~ make wiping electrical contact with a solder ball inserted into ~~said~~ an aperture.

Claim 12 (Canceled).

13 (Currently Amended). The device of claim 12 wherein said spring contact includes ~~contacts include~~ opposed contact arms, one of which extends upwardly and the other which extends downwardly to contact said printed circuit board.

14 (Currently Amended). The device of claim 13 wherein said printed circuit board has a land ~~lands~~ engaged by said spring ~~contacts~~ contact.

15 (Original). The device of claim 11 wherein said housing includes a protrusion on its upper surface to align a land grid array package with said housing.

16 (Currently Amended). The device of claim 15 wherein said ~~alignment feature~~ protrusion is L-shaped.

17 (Currently Amended). The device of claim 16 including two L-shaped ~~alignment features~~ protrusions opposed diagonally from one another on said housing.

18 (Original). The device of claim 11 including a ball grid array package engaged on said socket housing.

19 (Original). The device of claim 11 including a land grid array package engaged on said socket housing.